



JAMES

Design Parameters For The Additive Production Of Electronics

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Outline

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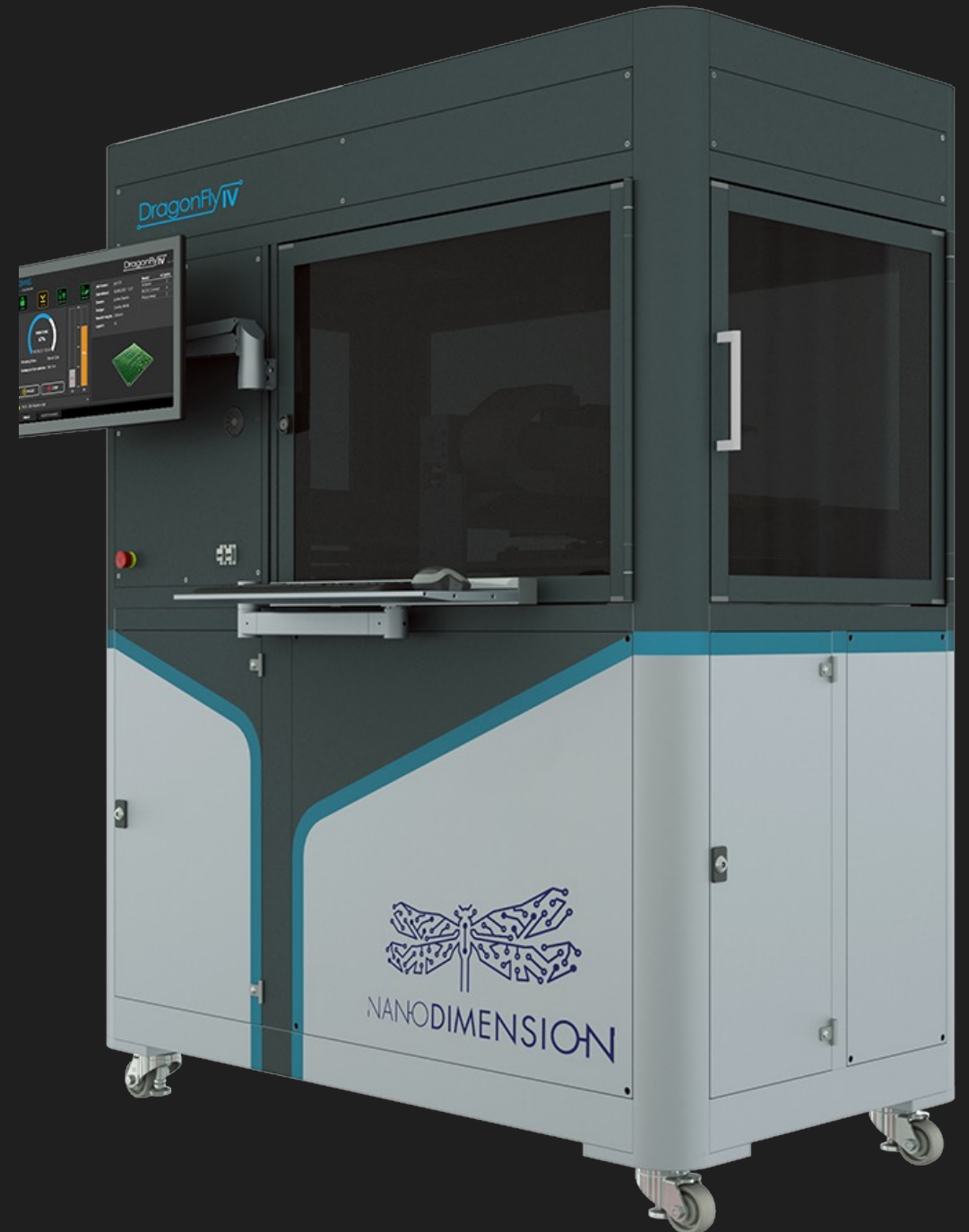


Goals

- Identify limiting factors for 3D-Electronics using Benchmark Tests
- Combine various Benchmarks to create a complete Test for different systems
- Tests are focused on manufacturability and **not** on performance
- Create a basic summary of results for future reference
- Identify issues and their causes
- Offer solutions for certain issues

Setup

- All tests are done on the DragonFly IV platform
 - Retrofitted LDM
 - Production DFIV
- Ohmic measurements on HM8118 LCR-meter
- Visual inspection using the Keyence VHX-3000
- Software development is done in MATLAB (R2021b)





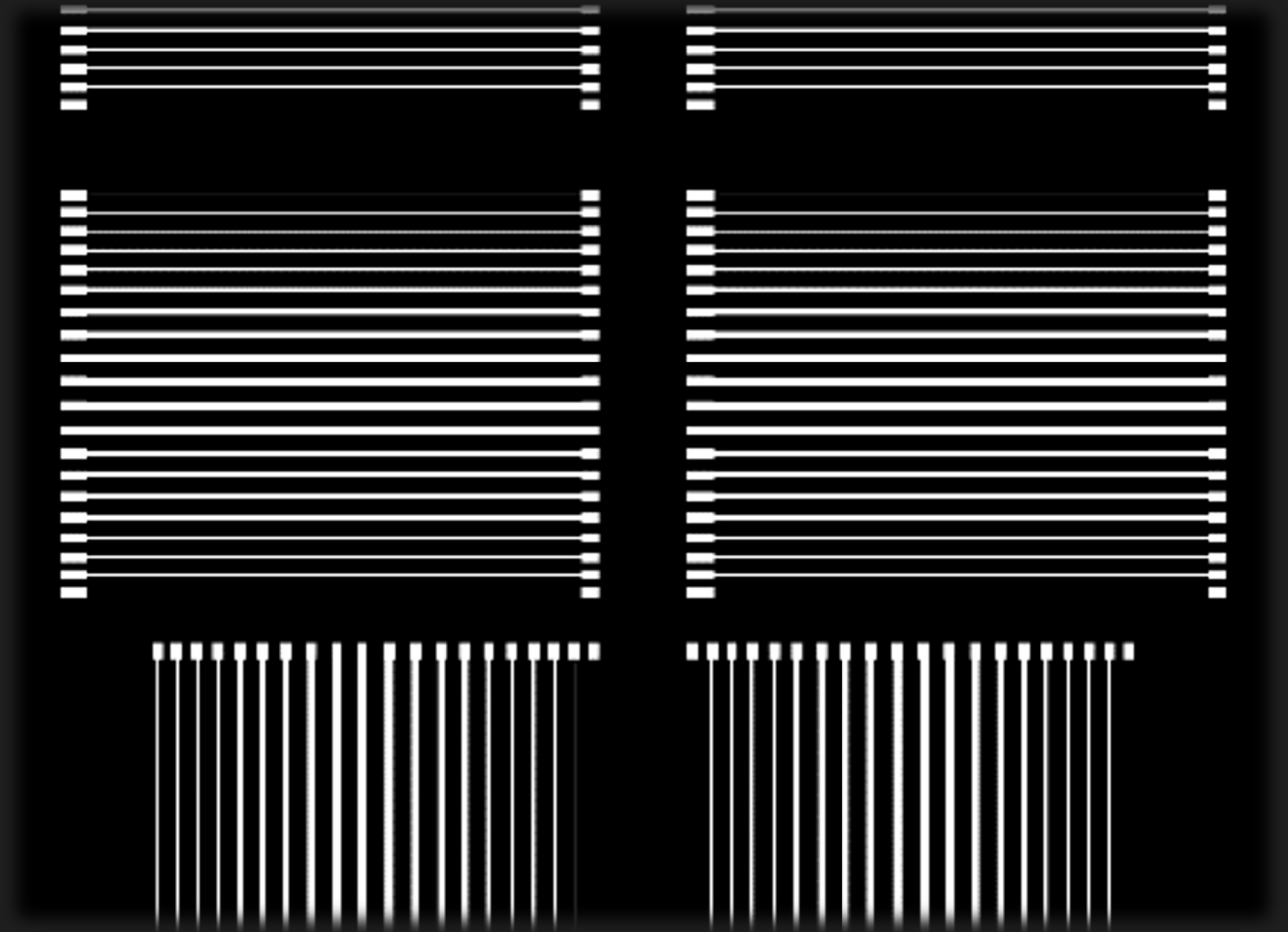
Order of Work

- Determine minimum dimensions in X and Y
- Development of reconstruction software
- Effects of different file formats
- Behaviour in the third dimension
- Development of the final Benchmark-test



Minimum Dimensions in X and Y Description

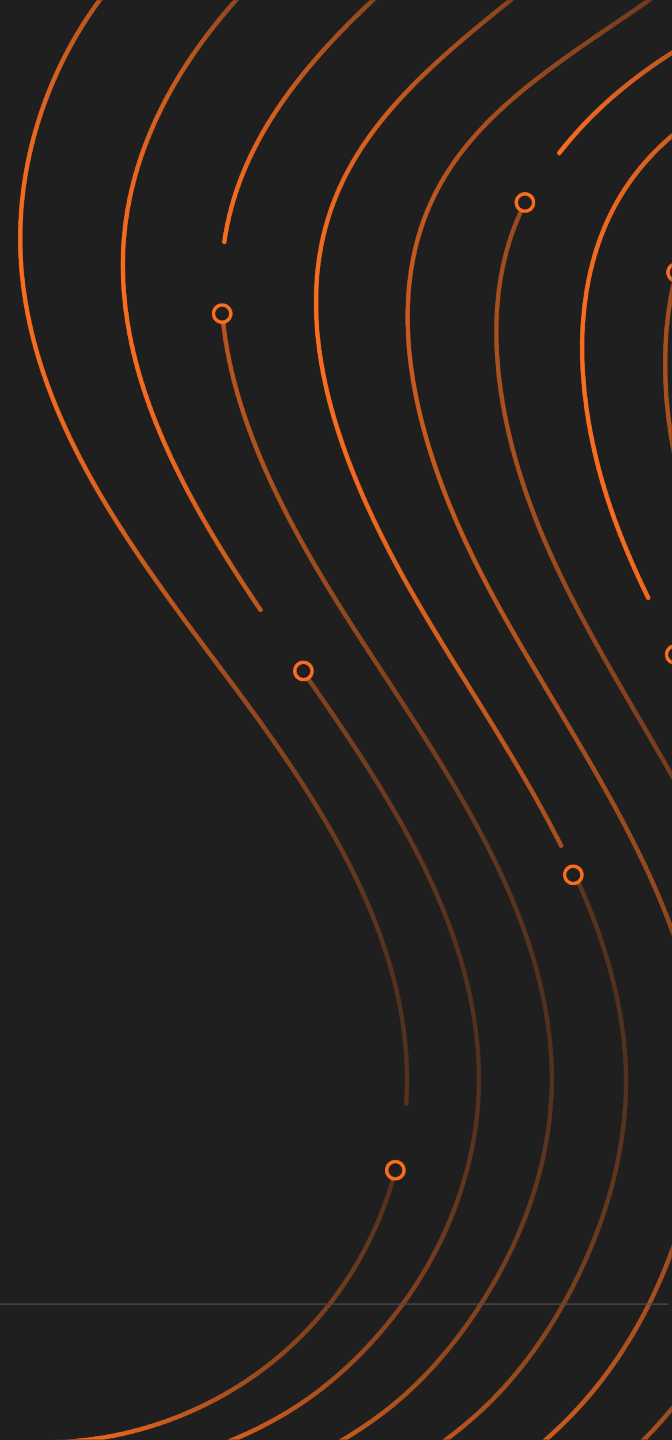
- Lines with a width between 1 to 10 Pixels were designed in Fusion360
- Lines were printed in both X and Y direction
- Lines were tested at different heights





Minimum Dimensions in X and Y Results

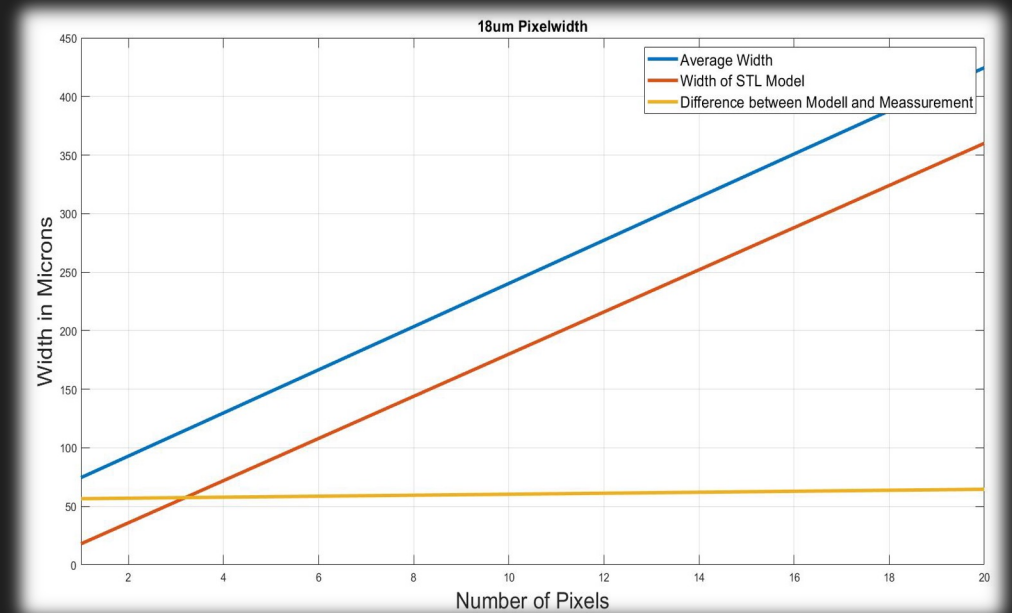
- All lines were intact and usable
- Width appears to be larger than the designed model
- Offset of approximately $40\mu\text{m}$ to $50\mu\text{m}$ or about $2/3$ pixels
- Effect can be seen on all tested Samples
- Number of Pixels appears to be correct





Minimum Dimensions in X and Y Explanation

- Slicing software creates files with pixels equivalent to $18\mu\text{m}$
- Actual size of the pixels is **not** $18\mu\text{m}$
- Size of pixels is **not** constant
- Samples between 1 to 10 pixels were tested
- Offset appears to be constant
- Difference between X and Y is negligible
- Difference between design and result can be estimated





Reconstruction program Overview

- Identification of errors through reconstruction of the files
 - Read individual images
 - Reduce size
 - Create stack
 - Generate a mesh
- Better visualization
- Find Errors before printing
 - Lower risk of failed prints
- Used for analysis of 3D Tests





Effects of different file formats

overview

STL-format

- The correct number of pixels is shown in the images
- Pixels are equal to $18\mu\text{m}$ in the respective models
- Spacing between structures is identical to the design
- Sliced models are as expected from the design

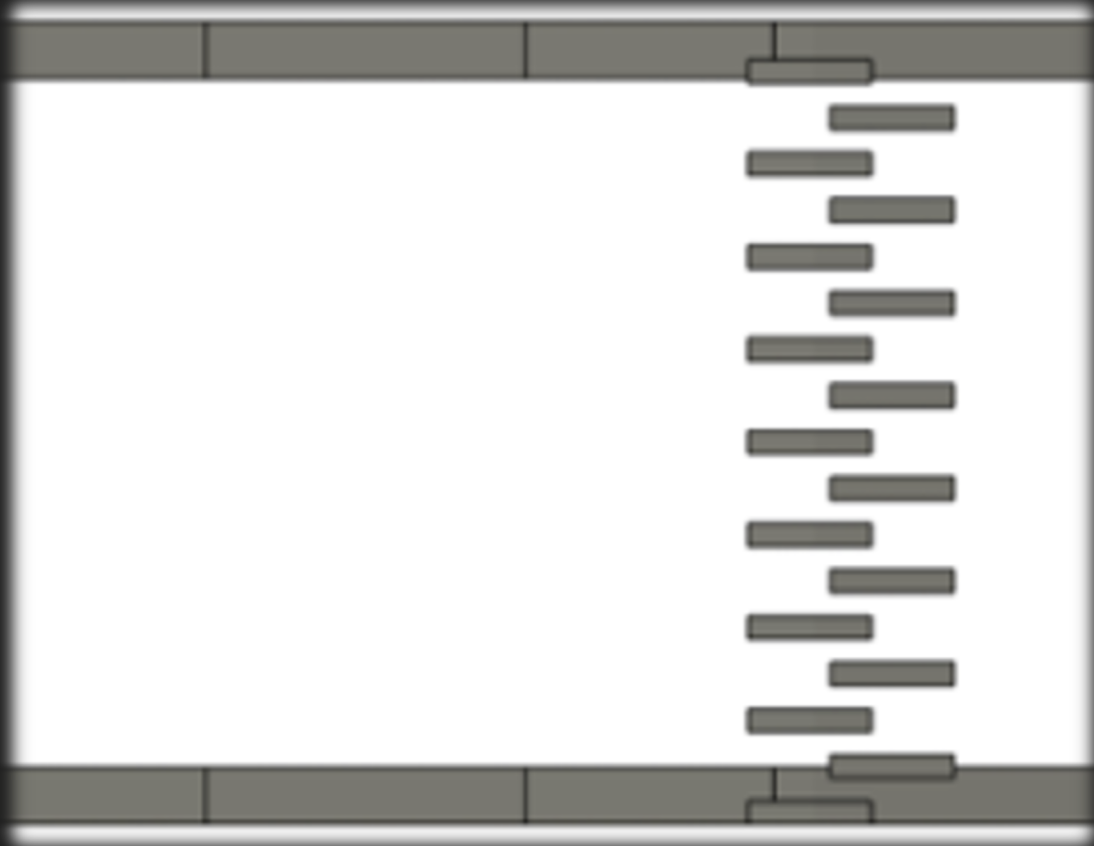
Gerber-format

- The number of pixels is on average two pixels lower than expected
- The represented width of the Pixels larger than $18\mu\text{m}$
- The spacing between the lines is not uniform and varies by up to two pixel
- The print jobs are warped compared to the original Gerber

Effects of different file formats

Summary

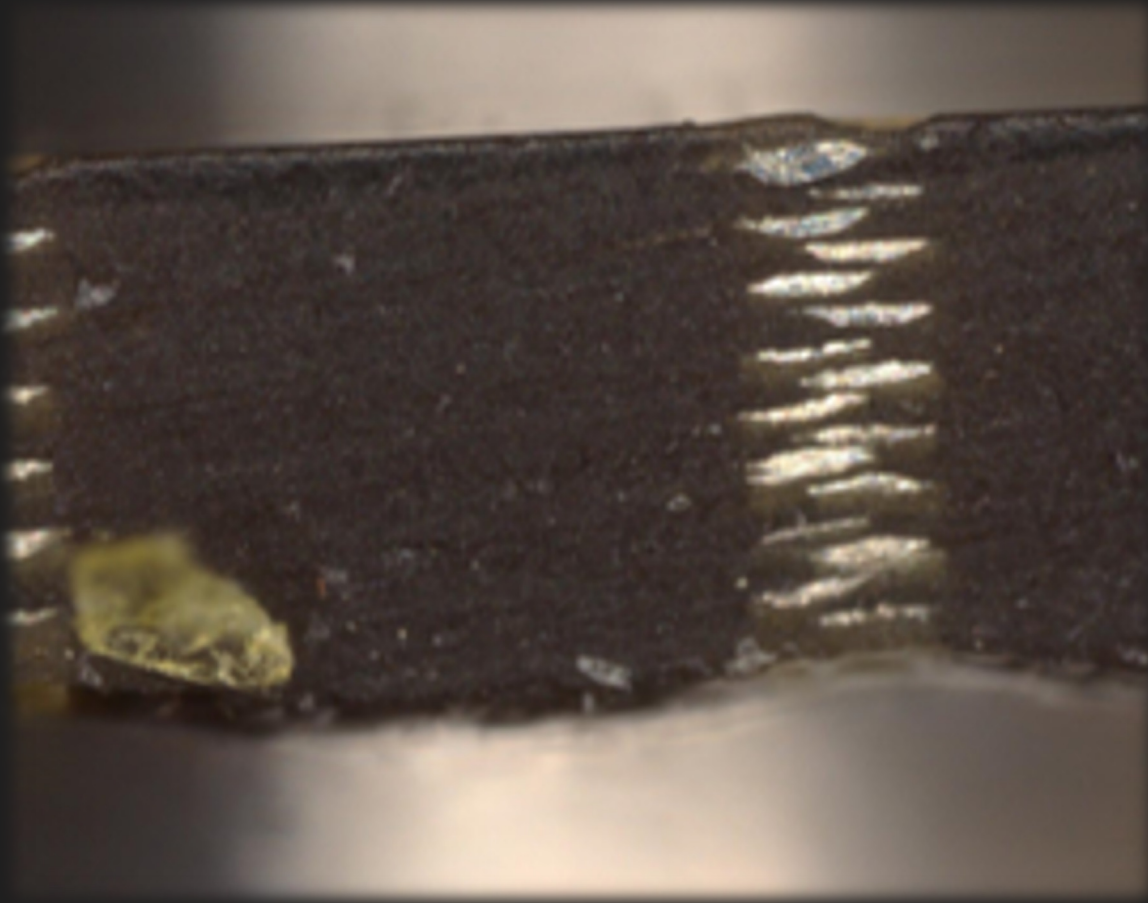
- Ecad files are processed differently than the STL-files
- **The manufacturer is aware of the issue**
- Fixes are done in the image files used during printing
- Actual limit of printed circuits is approx. **75 μ m**



Behavior in the third dimension Spacing in Z-Direction

Setup:

- Several staggered stacks of plates with a thickness of $20\mu\text{m}$
- Spacing between $10\mu\text{m}$ and $30\mu\text{m}$



Behavior in the third dimension Spacing in Z-Direction

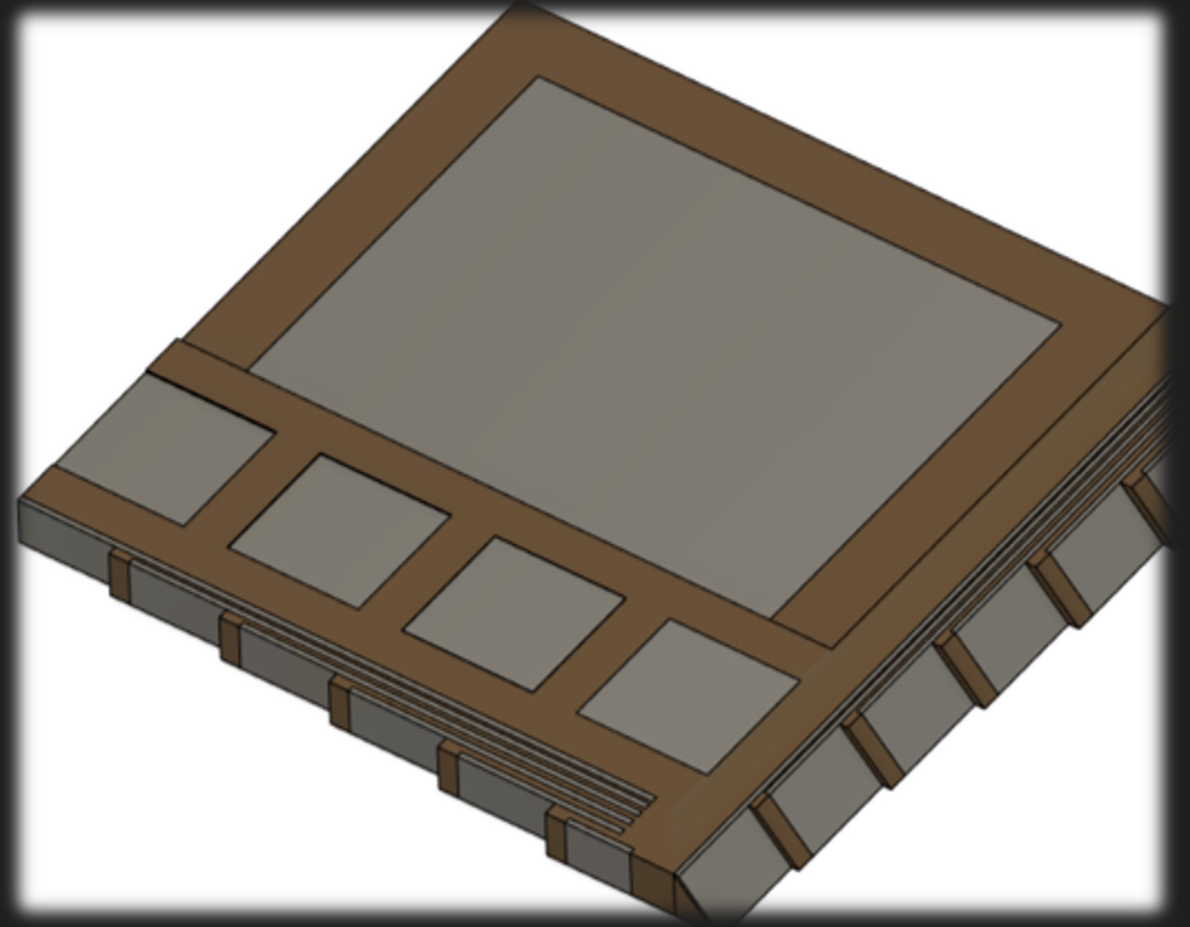
Result:

- Plate thickness is not constant in the final print
- Spacing between plates is not uniform
- Shorts occur between adjacent plates
- Results dependant on layer thickness of the machine



Behavior in the third dimension Spacing in Z-Direction

- **Setup:**
 - Vertically stacked plates with 10-40 μ m spacing
 - Vertical walls stacked with 36-126 μ m spacing
 - Angled walls at 45° with 36-126 μ m spacing
- **Results:**
 - Vertically spaced plates are isolated at 40 μ m
 - All vertical walls are shorted





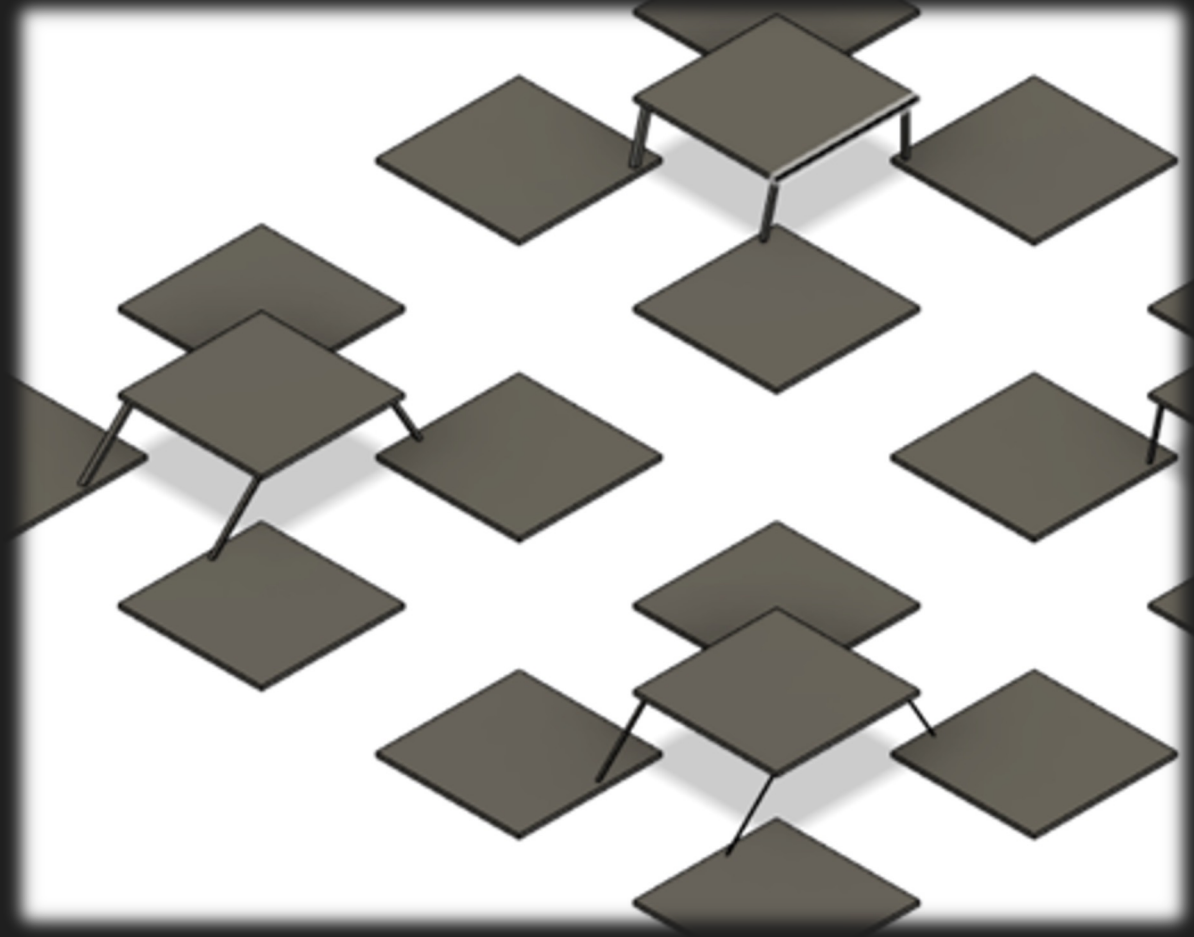
Behavior in the third dimension Vertical connections and bending Radius

Setup:

- Design of vertical connections with 45°, 60°, 75° and 90° angle

Result:

- All connections with 4 or above Pixels were functional
- 4 Pixels will be used as reference



Behaviour in the third dimension

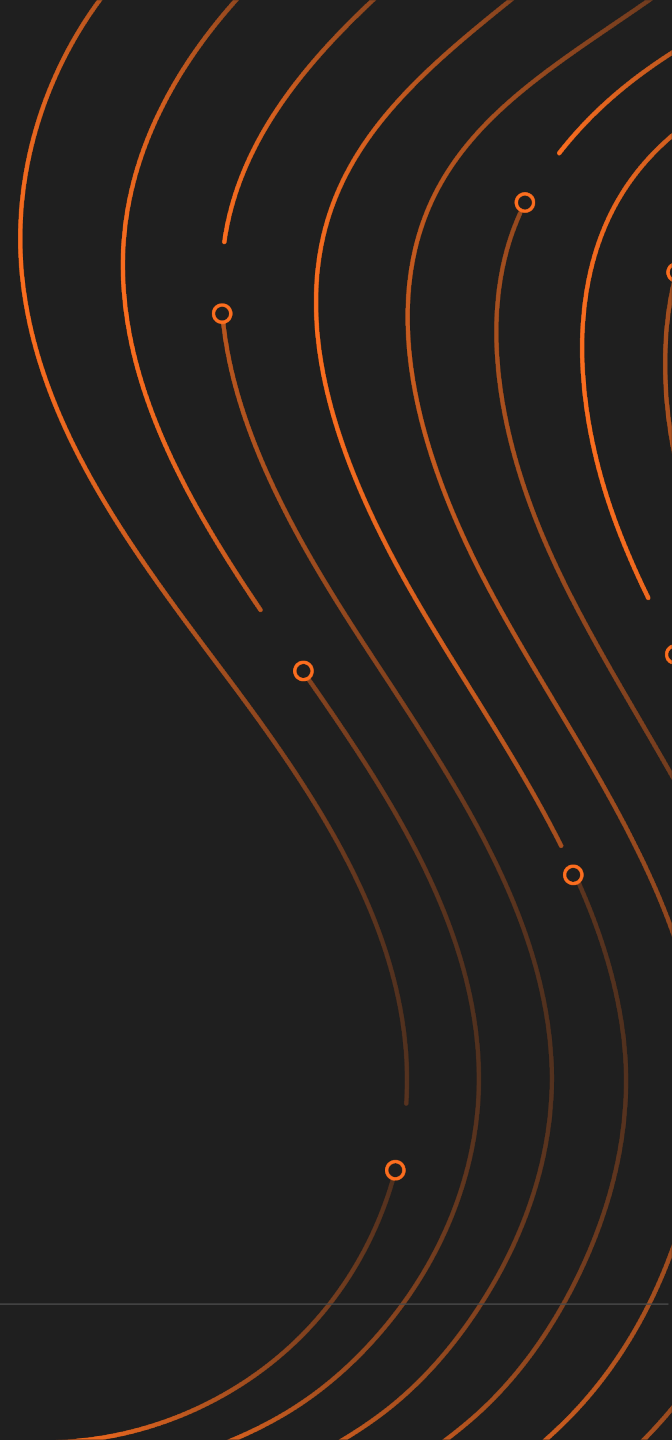
Vertical connections and bending Radius

Setup:

- Connections with a curve at the end to contact pads

Result:

- All connections were functional
- Resistance between different radii in XY was almost identical
- Resistance in Z-Direction increased with the Bend diameter
- Probable cause is the slicing behaviour

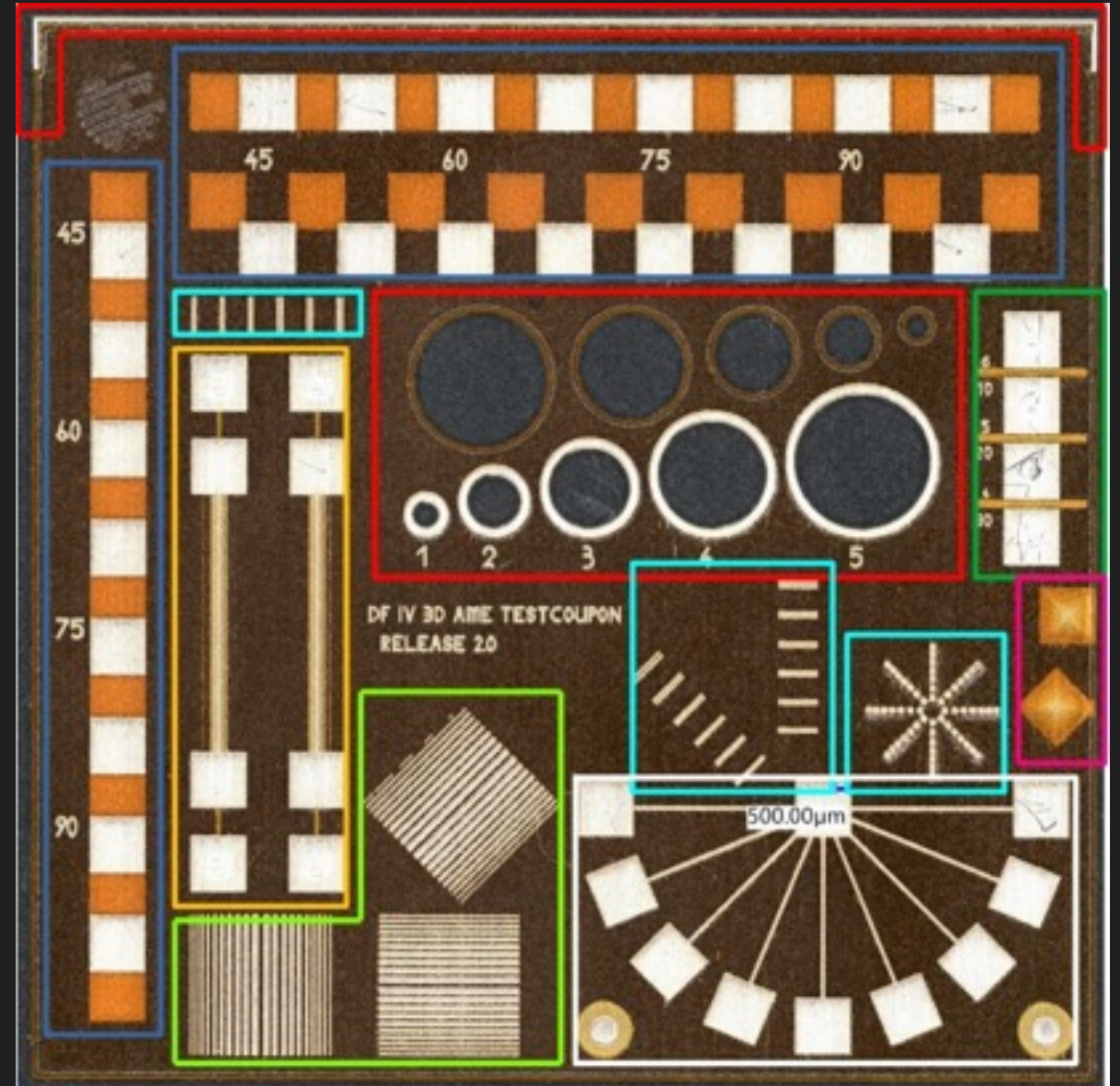




Final Benchmark-test Design

Design of eight segments:

- **RED:** determining of border sagging effects
- **CYAN:** spacing between lines and vertical structures
- **BLUE:** minimum Via and Bend sizes
- **WHITE:** Behavior for different angles
- **DARK GREEN:** spacing between plates in Z-direction
- **LIGHT GREEN:** pixel size in different directions
- **YELLOW:** Coax lines for spacing in 3D
- **Magenta:** Behavior of slicing



Final Benchmark-test Results

Important notes:

- Spacing in X/Y was determined using the Coax
- Spacing in Z is depending on the state of the machine
- 18 μm lines in 45° were broken
- Sagging is a rough estimation

	Design	Reality
Line width	36 μm	93 μm
Spacing X/Y	180 μm	126 μm
Spacing Z	30 μm	-/-
Via width	72 μm	130 μm
Pixel size	18 μm	74 μm -21 μm
Sagging	-/-	0.1785 μm

Summary and possible Solutions

Design rules

Aspect	Model	Reality	Notes
Minimum line width	36 μ m	93 μ m	1px lines are broken
Minimum Spacing X/Y	180 μ m	126 μ m	
Minimum Spacing Z	40 μ m	-/-	Depending on Printer
Minimum 3D-Via width	72 μ m	130 μ m	Depending on Printer
Pixel size X/Y	18 μ m	74 μ m-21 μ m	Only tested until 10px
Sagging per μ m in Z	-/-	0.1785 μ m	Verified for $Z \leq 560\mu$ m
Minimum Radius X/Y/Z	-/-	D/2	D= Via width



Summary and possible Solutions Issues

- Most issues are related to the software and missing documentation from the manufacturer
- Pixels are not identical to the given specifications
- Gerber are adjusted to solve the issues, but STL is not adjusted
- **Specifications for Gerber-Files are not applicable for STL**





Summary and possible Solutions

Adjust the design accordingly:

- A lot of effort
- Needs to be done on every model

Implement function in the slicer:

- No additional work required
- Needs to be done by the manufacturer

Development of a standalone Program:

- Automation of the process
- Use of additional programs increases work steps



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